

IN THE CLAIMS:

Please amend the claims as follows:

1. (Currently Amended) A multi-chip module system comprising:
a substrate having at least a first position having, in turn, a predetermined configuration for locating a first semiconductor device thereat and having at least one other second ~~vacant~~ position having, in turn, a predetermined configuration for locating a second semiconductor device thereat on the multi-chip module system, the at least one other second ~~vacant~~ position having no semiconductor device located thereat until a semiconductor device is installed to replace a defective semiconductor device at another position;
a first semiconductor device located in the at least first position of the substrate for use in the multi-chip module system, the first semiconductor device having a first predetermined performance characteristic, said first semiconductor device having been burned in at said at least first position on said substrate; and
a second known-good-die located at the at least one other second ~~vacant~~ position .
2. (Currently Amended) The multi-chip module system of claim 1, further comprising:
the at least one other third ~~vacant~~ position having the predetermined configuration for locating the second semiconductor device thereat which is substantially the same as the predetermined configuration of the first position.
3. (Canceled)

4. (Currently Amended) The multi-chip module system of claim 1, further comprising:
the at least one other ~~vacant~~ position having the predetermined configuration for locating the second semiconductor device thereat; and
the second semiconductor device having a second predetermined performance characteristic of at least substantially twice that of the first predetermined performance characteristic of the first semiconductor device.

5 (Currently Amended) A multi-chip module system comprising:
a substrate having a first position having, in turn, a predetermined configuration for locating a first semiconductor device thereat, having a second position having, in turn, a predetermined configuration for locating a second semiconductor device thereat, and having at least one other third ~~vacant~~ position having, in turn, a predetermined configuration for locating a third semiconductor device thereat on the multi-chip module system, the at least one other vacant position having no semiconductor device located thereat until a semiconductor device is installed to replace a defective semiconductor device at another position;
the first semiconductor device located in the first position of the substrate for use in the multi-chip module system, the first semiconductor device having a first predetermined performance characteristic; and
a second known-good-die semiconductor device located in the second position of the substrate for use in the multi-chip module system, the second semiconductor device having a second predetermined performance characteristic, said first and second semiconductor devices have been burned in at said first and second positions, respectively, on said substrate.

6. (Currently Amended) The multi-chip module system of claim 5, further comprising:
the at least one other third ~~vacant~~ position having a predetermined configuration for locating a third semiconductor device thereat which is substantially the same as the predetermined configuration of the first position.

7. (Currently Amended) The multi-chip module system of claim 5, further comprising:
the at least one other third ~~vacant~~ position having a predetermined configuration for locating a third semiconductor device thereat; and
the third semiconductor device having a predetermined performance characteristic substantially similar to that of the first predetermined performance characteristic of the first semiconductor device.

8. (Canceled)

9. (Canceled)

10. (Canceled)

11. (Previously Presented) The multi-chip module system of claim 5, wherein the first semiconductor device comprises a memory device.

12. (Previously Presented) The multi-chip module system of claim 5, wherein the second semiconductor device comprises a memory device.

13. (Previously Presented) The multi-chip module system of claim 5, wherein the first semiconductor device comprises a microprocessor device.

14. (Previously Presented) The multi-chip module system of claim 5, wherein the second semiconductor device comprises a microprocessor device.

15. (Previously Presented) The multi-chip module system of claim 5, wherein the multi-chip module system comprises a single in-line memory module system.

16. (Currently Amended) The multi-chip module system of claim 5, further comprising:
a third semiconductor device; and
an adapter connected to the third semiconductor device, the adapter having a configuration for connecting the adapter to the at least one other third ~~vacant~~ position on the substrate to allow connection of the third semiconductor device to the substrate.

17. (Currently Amended) A multi-chip module system comprising:
a substrate having two opposing sides, said substrate having a first position having, in turn, a predetermined configuration for locating a first semiconductor device thereat, having a second position having, in turn, a predetermined configuration for locating a second semiconductor device thereat, having a third ~~first-vacant~~ position having, in turn, a predetermined configuration for locating a third semiconductor device thereat, the third ~~first-vacant~~ position having no semiconductor device located thereat until a semiconductor device is installed to replace a defective semiconductor device at another position, and having a fourth ~~second-vacant~~ position having, in turn, a predetermined configuration for locating a fourth semiconductor device thereat on the multi-chip module system, the fourth ~~second-vacant~~ position having no semiconductor device located thereat until a semiconductor device is installed to replace a defective semiconductor device at another position;
the first semiconductor device located in the first position of the substrate for use in the multi-chip module system, the first semiconductor device having a first predetermined performance characteristic; and

a second known-good-die semiconductor device located in the second position of the substrate for use in the multi-chip module system, the second semiconductor device having a second predetermined performance characteristic, said first device being burned in at said first position on said substrate.

18. (Currently Amended) The multi-chip system module of claim 17, wherein: the third ~~first-vacant~~ position and the fourth ~~second-vacant~~ position are on opposing sides of the substrate.

19. (Currently Amended) A multi-chip module system comprising:
a substrate having at least a first predetermined configuration position for locating a first semiconductor device thereat and having at least one other second ~~vacant~~ predetermined configuration position for locating a second semiconductor device thereat on the multi-chip module system, the at least one other second ~~vacant~~ position having no semiconductor device located thereat until a semiconductor device is installed to replace a defective semiconductor device at another position;
the first semiconductor device located in the at least the first predetermined configuration position of the substrate for use in the multi-chip module system, the first semiconductor device having a first predetermined performance characteristic, said first semiconductor device being burned in at said first predetermined configuration position on said substrate; and
a second known-good-die located at the at least one other second predetermined configuration ~~vacant~~ position.

20. (Currently Amended) The multi-chip module system of claim 19, further comprising:
the at least one other third ~~vacant~~ predetermined configuration position for locating the second semiconductor device thereat which is substantially the same as the predetermined configuration of the first position.

21. (Currently Amended) The multi-chip module system of claim 19, further comprising:
the at least one other third ~~vacant~~ predetermined configuration position having a predetermined configuration for locating the second semiconductor device thereat; and
the second semiconductor device having a predetermined performance characteristic substantially similar to that of the first predetermined performance characteristic of the first semiconductor device.

22. (Canceled)

23. (Currently Amended) A multi-chip module system comprising:
a substrate having a first predetermined configuration position for locating a first semiconductor device thereat, having a second predetermined configuration position for locating a second semiconductor device thereat, and having at least one other third ~~vacant~~ predetermined configuration position for locating a third semiconductor device thereat on the multi-chip module system, the at least one other third ~~vacant~~ position having no semiconductor device located thereat until a semiconductor device is installed to replace a defective semiconductor device at another position;
the first semiconductor device located in the first predetermined configuration position of the substrate for use in the multi-chip module system, the first semiconductor device having a first predetermined performance characteristic; and
a known-good-die second semiconductor device located in the second predetermined configuration position of the substrate for use in the multi-chip module system, the second semiconductor device having a second predetermined performance characteristic.

24. (Currently Amended) The multi-chip module system of claim 23, further comprising:
the at least one other ~~third~~ ~~vacant~~ predetermined configuration position for locating the third semiconductor device thereat which is substantially the same as the predetermined configuration of the first position.

25. (Currently Amended) The multi-chip module system of claim 23, further comprising:
the at least one other ~~third~~ ~~vacant~~ predetermined configuration position for locating the third semiconductor device thereat; and
the third semiconductor device having a third predetermined performance characteristic substantially similar to that of the first predetermined performance characteristic of the first semiconductor device.

26. (Canceled)

27. (Canceled)

28. (Canceled)

29. (Original) The multi-chip module system of claim 23, wherein the first semiconductor device comprises a memory device.

30. (Original) The multi-chip module system of claim 23, wherein the second semiconductor device comprises a memory device.

31. (Original) The multi-chip module system of claim 23, wherein the first semiconductor device comprises a microprocessor device.

32. (Original) The multi-chip module system of claim 23, wherein the second semiconductor device comprises a microprocessor device.

33. (Original) The multi-chip module system of claim 23, wherein the multi-chip module system comprises a single in-line memory module system.

34. (Currently Amended) The multi-chip module system of claim 23, further comprising:
an adapter connected to the third semiconductor device, the adapter having a configuration for connecting the adapter to the at least one other third ~~vacant~~ predetermined configuration position on the substrate to allow connection of the third semiconductor device to the substrate.

35. (Currently Amended) A multi-chip module system comprising:
a substrate having two opposing sides, said substrate having a first predetermined configuration position for locating a first semiconductor device thereat, having a second predetermined configuration position for locating a second semiconductor device thereat, having a third ~~first~~ ~~vacant~~ predetermined configuration position for locating a third semiconductor device thereat, the third ~~first~~ ~~vacant~~ predetermined configuration position having no semiconductor device located thereat until a semiconductor device is installed to replace a defective semiconductor device at another position, and having a fourth ~~second~~ ~~vacant~~ predetermined configuration for locating a fourth semiconductor device thereat on the multi-chip module system, the second vacant predetermined configuration position having no semiconductor device located thereat until a semiconductor device is installed to replace a defective semiconductor device at another position;
the first semiconductor device located in the first predetermined configuration position of the substrate for use in the multi-chip module system, the first semiconductor device having a first predetermined performance characteristic; and

a known-good-die second semiconductor device located in the second predetermined configuration position of the substrate for use in the multi-chip module system, the second semiconductor device having a second predetermined performance characteristic.

36. (Currently Amended) The multi-chip system module of claim 35, wherein: the third ~~first vacant~~ predetermined configuration position and the fourth ~~second vacant~~ predetermined configuration position are located on opposing sides of the substrate.